

APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C ⁽¹⁾	STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C ⁽²⁾	
	VOLTAGE	50 V AC	STORAGE HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)	
	CURRENT	0.5 A	OPERATING HUMIDITY RANGE		
SPECIFICATIONS					
ITEM	TEST METHOD		REQUIREMENTS	QT	AT
CONSTRUCTION					
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x	x
MARKING	CONFIRMED VISUALLY.			x	x
ELECTRIC CHARACTERISTICS					
CONTACT RESISTANCE	100 mA(DC OR 1000Hz)		70 mΩ MAX .	x	—
INSULATION RESISTANCE	100 V DC.		100 MΩ MIN.	x	—
VOLTAGE PROOF	150 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x	x
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES	MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 84 N MAX. WITHDRAWAL FORCE: 10.3 N MIN.	x	—
MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: Δ VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
VIBRATION	FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
SHOCK	490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x	—
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: Δ VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② INSULATION RESISTANCE :100 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER:WITHIN 2~3 MIN)			x	—
COLD	EXPOSED AT -55°C, 96 h		① CONTACT RESISTANCE: Δ VARIATION FROM INITIAL VALUE 20 mΩ OR LESS. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	—
DRY HEAT	EXPOSED AT 85°C, 96 h			x	—
SULFUR DIOXIDE	EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		① NO DEFECT SUCH AS CORROSION WHICH IMPAIRS THE FUNCTION OF CONNECTOR. ② CONTACT RESISTANCE: Δ VARIATION FROM INITIAL VALUE 20 mΩ OR LESS.	x	—
RESISTANCE TO SOLDERING HEAT	1)REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.			NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	x	—
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
Δ	4	DIS-F-005857	KT. D01	KI. HIROKAWA	11. 11. 24
REMARKS ⁽¹⁾ INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. ⁽²⁾ "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB.			APPROVED	HS. OKAWA	11. 08. 22
			CHECKED	KI. HIROKAWA	11. 08. 12
			DESIGNED	KT. D01	11. 08. 12
Unless otherwise specified, refer to JIS-C-5402.			DRAWN	KT. D01	11. 08. 12
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC4-336348-00
HRS	SPECIFICATION SHEET		PART NO.	FX20-120S-0. 5SV10	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL570-1111-9-00	Δ 1/1